

# **Application Data Sheet**

## **Application Information**

Application Type::	Regular
Subject Matter::	Utility
Title::	Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages
Attorney Docket Number::	CPAC 1017-5 D3
Total Drawing Sheets::	7
Small Entity?::	No

## **Applicant Information**

Applicant Authority Type:	Inventor
Primary Citizenship Country:	US
Status:	Full Capacity
Given Name:	Marcos
Family Name:	Karnazos
City of Residence:	Palo Alto
State or Province of Residence:	CA
Country of Residence:	US
Street of mailing address:	535 Lytton Avenue
City of mailing address:	Palo Alto
State or Province of mailing address:	CA
Country of mailing address:	US
Postal or Zip Code of mailing address:	94301

## Correspondence Information

Correspondence Customer Number:: 22470

## Representative Information

Representative Customer Number::	22470	
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## Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	An application claiming the benefit under 35 USC 119 (e)	60411590	17 September 2002

## Assignee Information

Assignee name:: ChipPAC, Inc.  
Street of mailing address:: 47400 Kato Road  
City of mailing address:: Fremont  
State or Province of mailing address:: CA  
Country of mailing address:: US  
Postal or Zip Code of mailing address:: 94538